

TMS320DM644x Power Reference Design

This design is a modification of SLVR303 using the UCD9081 digitally programmable power supply sequencer.

1 Features

- Highly flexible sequencing design using the UCD9081, which is a digitally programmable 8-channel power supply sequencer
- Downloadable setup file for UCD9081 automatically configures sequencing requirements for the DM644x
- Design optimized for 5V input voltage

2 Introduction

This reference design is for the TMS320DM644x and accounts for voltage, current, and sequencing requirements. This design is a modification to SLVR303 reference design using the UCD9081 sequencer rather than discrete components for sequencing. The use of the UCD9081 adds significant flexibility to the design and can reduce overall system component count. The UCD9081 also adds monitoring functions for under-voltage and over-voltage as well as other monitoring features. The operating input voltage is 4.5V to 5.5V. This design is optimized for flexibility and low system cost.

3 Requirements

The TMS320DM644x requires three input rails, which are outlined in Table 1.

POWER REQUIREMENTS FOR TMS320DM644x								
	Pin Name	Voltage (V)	lmax (mA)	Tolerance	Sequencing Order	Timing Delay		
Core	CVDD, VDDA1P1V, VDDA1P2LDO, CBVDDDSP	1.2	1700	±5%	1			
I/O	DVDD33, USB_VDDA3P3	3.3	25	±4.5%	2	IO supplies must be powered up after core supplies have been powered up.		
I/O	DVDD18, DVDDR2, DDR_VDDDLL, PLLVDD18, VDDA1P8V, USB_VDD1P8, MXVDD, M24VDD	1.8	170	±5%	2	IO supplies must be powered up within 100ms after core supply is stable.		

Table 1. DM644x Power Requirements

The rails must power-up and power-down in the proper order. On power-up, the 1.2V should come up first then 1.8V and 3.3V together or 1.8V then 3.3V.

1



Block Diagram

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4 Block Diagram

See the schematic for further detail.

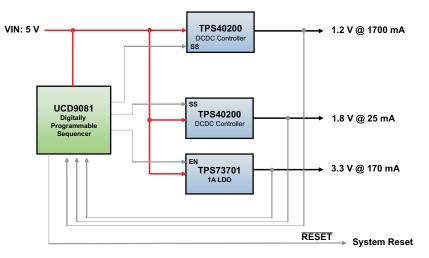


Figure 1. Block Diagram of Power Design

4.1 Power-Up Waveforms

The figure below shows the power-up waveforms for the PMP4188 design.

- Ch1:5V input voltage
- Ch2:1.2V
- Ch3:1.8V
- Ch4:3.3V

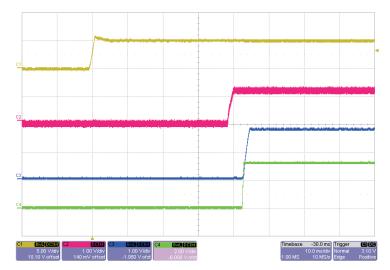
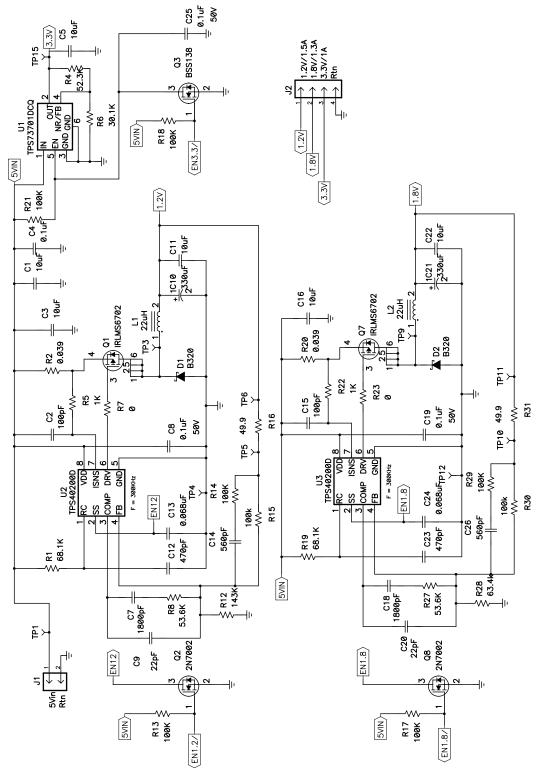


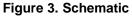
Figure 2. Power-up Waveforms



5 Schematics and Bill of Materials

5.1 Schematics







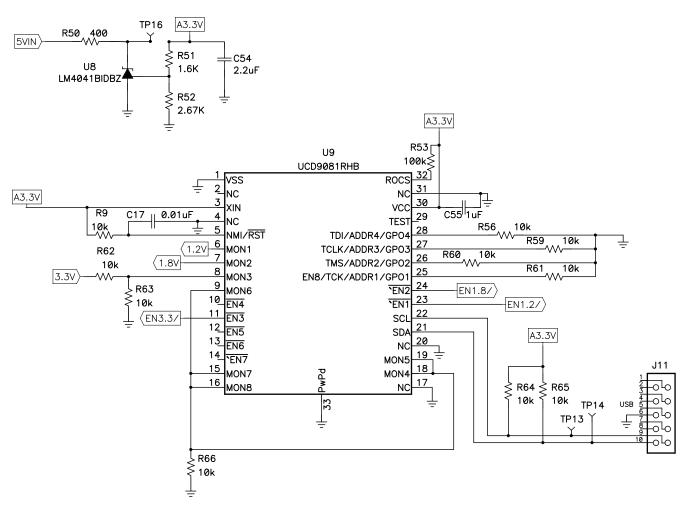


Figure 4. Schematic



5.2 Bill of Materials

Table 2. PMP4118_REVB BOM

Count	RefDes	Value	Description	Size	Part Number	MFR
3	C1, C3, C16	10 μF	Capacitor, Ceramic, 10V, X7R, 20%	0805	Std	Std
2	C10, C21	330 μF	Capacitaor, Aluminum, 10V, 160 m Ω , ±20%	$0.328 \times 0.390 \text{ inch}$	EEVFK1A331P	Panasonic
2	C11, C22	10 μF	Capacitor, Ceramic, 6.3V, X7R, 20%	0805	Std	Std
1	C12	470 pF	Capacitor, COG, 50V, 20%	0603	Std	Std
2	C13, C24	0.068 μF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
2	C14, C26	560 pF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
1	C17	0.01 μF	Capacitor, Ceramic, 10V, X7R, 20%	0603	Std	Murata
2	C2. C15	100 pF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
1	C23	470 pF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
1	C4	0.1 μF	Capacitor, Ceramic, 10V, X7R, 20%	0603	Std	Std
1	C5	10 μF	Capacitor, Ceramic, 6.3V, X7R, 20%	0805	Std	Std
1	C54	2.2 μF	Capacitor, Ceramic, 6.3V, X7R, 20%	0805	Std	Std
1	C55	1 μF	Capacitor, Ceramic, 6.3V, X5R	0603	Std	Std
2	C7, C18	1800 pF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
3	C8, C19, C25	0.1 μF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
2	C9, C20	22 pF	Capacitor, Ceramic, 50V, COG, 20%	0603	Std	Std
2	D1, D2	B320	Diode, Schottky, 3A, 30V	SMC	B330	Diodes Inc.
1	J1	PTC36SAAN	Header, Male 2-pin, 100mil spacing, (36-pin strip)	0.100 inch x 2	PTC36SAAN	Sullins
1	J11	2510-6002UB	Connector, Male Straight 2x10 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	2510-6002UB	3M
1	J2	PTC36SAAN	Header, Male 4-pin, 100mil spacing, (36-pin strip)	0.100 inch x 4	PTC36SAAN	Sullins
2	L1, L2	22 μH	Inductor, SMT, 3.7A, 40mΩ	0.492 sq"	DR125-220	Coiltronics
2	Q1, Q7	IRLMS6702	MOSFET, P-ch, -2.3A, 200mΩ	Micro6	IRLMS6702	IR
2	Q2, Q8	2N7002	MOSFET, N-ch, 60-V, 115-mA, 1.2 Ω	SOT23	2N7002DICT	Vishay-Liteon
1	Q3	BSS138	MOSFET, N-ch, 50-V, 200-mA, 3.5 Ω	SOT23	BSS138	Diodes, Inc.
2	R1, R19	68.1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	143K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
6	R13, R14, R17, R18, R21, R29	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R15, R30	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R16, R31	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R2, R20	0.039	Resistor, Chip, 1/3W, 5%	1210	ERJ- L14K39MU	Panasonic
1	R28	6.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	52.3K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R5, R22	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R50	400	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R51	1.6K	Resistor, Chip, 1/16W, 0.1%	0603	Std	Std
1	R52	2.67K	Resistor, Chip, 1/16W, 0.1%	0603	Std	Std
1	R53	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	30.1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R7, R23	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R8, R27	53.6K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
10	R9, R56, R59–R66	10k	Resistor, Chip, 1/16W, 5%	0603	Std	Std
9	TP1, TP3, RP6, TP9, TP11, TP13–TP16	5000	Test point, Red, thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP4, TP12	5011	Test Point, Black, Thru hole	0.125 x 0.125 inch	5011	Keystone
2	TP5, RP10	5013	Test Point, Orange, Thru hole	0.125 x 0.125 inch	5013	Keystone
1	U1	TPS73701DCQ	IC, Cap-free NMOS, 400mA LDO Regulator with Reverse current protection	SOT223-6	TPS73701DCQ	TI



Table 2. PMP4118_REVB BOM (continued)

Count	RefDes	Value	Description	Size	Part Number	MFR	
2	U2, U3	TPS402000D	IC, Low cost sync buck controller	SO-8	TPS40200D	TI	
1	U8	LM4041BIDBZ	IC, Micropower shunt voltage reference 100 ppm/°C, 45μA–12mA, Adjustable	SOT23	LM4041BIDB	ті	
1	U9	UCD9081RHB	IC, Power supply sequencer and monitor	QFN-32	UCD9081RHB	ТΙ	
Notes: 1.	Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.						
2.	These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.						
3.	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.						

4. Ref designators marked with an asterisk (***) cannot be substituted. All other components can be substituted with equivalent MFG's components.

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